

# PROCEEDINGS OF SPIE

## ***MEMS/MOEMS Technologies and Applications III***

**Jung-Chih Chiao**

**Xuyuan Chen**

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*Editors*

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## Introduction

This conference, MEMS/MOEMS Technologies and Applications, is part of SPIE Photonics Asia, held at the Jiuha Grand Convention and Exhibition Center in Beijing, China, on 11–15 November 2007.

A big thanks is due to the symposium organizers, SPIE and Chinese Optical Society, and to the symposium chairs, Professors Brian Culshaw and Bingkun Zhou, for their splendid overall technical planning, contributions, and local arrangements. The warm and thoughtful local arrangement committees have made a great expression of Chinese hospitality. A special thanks goes to the international program committee for their support in reviewing papers and inspiration in conference planning. We thank SPIE proceedings staff for their skillful organizing and editing.

Finally, our appreciation must go to the authors for sharing their work and ideas. The enthusiasm and interaction shown during the conference among authors and attendees have greatly rewarded us.

**J.-C. Chiao**  
**Xuyuan Chen**  
**Xinxin Li**  
**Zhaoying Zhou**

